

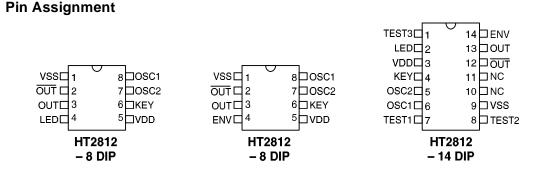
# HT2812 Single Sound Generator

#### Features

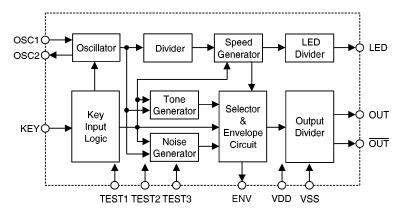
- Single power supply: 2.4V~3.3V
- Low standby current at 3V, 1μA (Typ.)
- Auto power-off function
- Speaker or direct piezo application
- Built-in envelope control circuit
- 1Hz~8Hz programmable LED flash output
- Minimum external components

#### **General Description**

The HT2812 is a CMOS LSI chip designed for use in sound effect products. It is equipped with tone circuit, noise circuit, and other control logic to generate different sounds including rifle gun, machine gun, booming sound, door bell, alarm etc. The customer supplied sound source can be analyzed and programmed into an internal ROM by changing a mask layer during device fabrication. The HT2812 is suitable for various toy applications.



#### **Block Diagram**

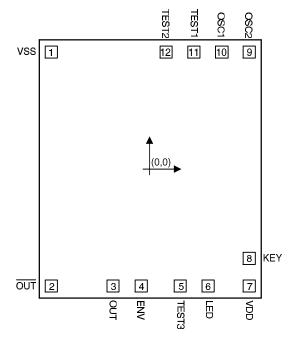


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### HT2812

#### **Pad Coordinates**



Pad No.	X	Y		
1	-27.127	32.3		
2	-27.127	-32.3		
3	-10.127	-32.3		
4	-2.307	-32.3		
5	8.488	-32.3		
6	16.138	-32.3		
7	27.528	-32.3		
8	27.528	-24.65		
9	27.528	32.3		
10	19.878	32.3		
11	12.228	32.3		
12	4.578	32.3		

Chip size :  $67 \times 72 \text{ (mil)}^2$ 

\* The IC substrate should be connected to VDD in the PCB layout artwork.

#### **Absolute Maximum Ratings\***

Supply Voltage0.3V to 5V	Storage Temperature50°C to 125°C
Input VoltageVSS-0.3 to VDD+0.3V	Operating Temperature0°C to 70°C

\*Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damageto the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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(Ta=25°C)

### **Electrical Characteristics**

Symbol	Parameter	Test Conditions		Min	<b>T</b>	Mari	T lost a
		VDD	Conditions	Min.	Тур.	Max.	Units
V <sub>DD</sub>	Operating Voltage	3V	_	2.4	3	3.3	V
I <sub>STB</sub>	Standby Current	3V	_		1	5	μΑ
I <sub>DD</sub>	Operating Current	3V	No load		300	600	μΑ
Іон	Output Source Current	3V	V <sub>OH</sub> =2.5V	-1	-2	_	mA
IOL	Output Sink Current	3V	$V_{OL}=0.5V$	1	2	—	mA
I <sub>ENV</sub>	ENV Source Current	3V	V <sub>OH</sub> =2.5V	-1	-2	—	mA
ILED	LED Source Current	3V	V <sub>OH</sub> =2.5V	-1	-2	_	mA
Fosc	Oscillator Frequency	_	R=330kΩ		64	_	kHz
V <sub>IH</sub>	"H" Input Voltage	3V	_	2.4		_	V
VIL	"L" Input Voltage	3V	_			0.6	V

## Pad Description

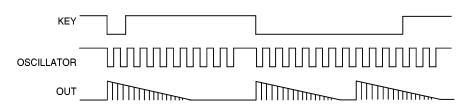
Pad No.	Pad Name	I/O	Description	
1	VSS	_	Negative power supply, GND	
2	OUT	0	Sound output pad, out of phase to pad 3	
3	OUT	0	Sound output pad	
4	ENV	0	Sound envelope control pad	
5	TEST3	Ι	For IC test only	
6	LED	0	LED flash output pad	
7	VDD	_	Positive power supply	
8	KEY	Ι	Key input pad, low active	
9	OSC2	0	Oscillator output pad	
10	OSC1	Ι	Oscillator input pad	
11	TEST1	Ι	For IC test only	
12	TEST2	Ι	For IC test only	

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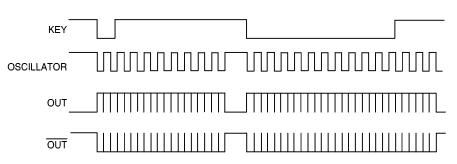


### **Timing Diagram**

With an envelope



No envelope

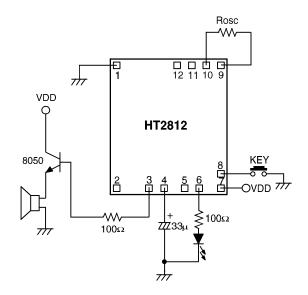


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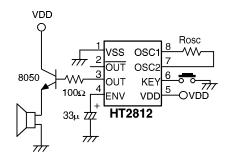


### **Application Circuits**

Speaker output with an envelope



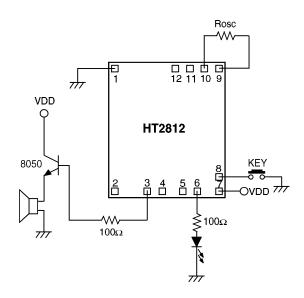
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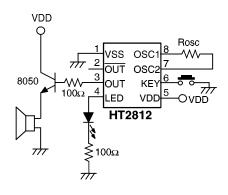
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#### Speaker output without an envelope



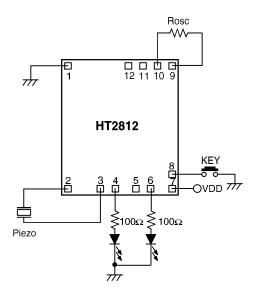
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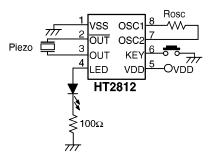
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#### Piezo output without an envelope



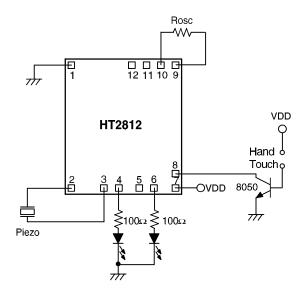
\* The IC substrate should be connected to VDD in the PCB layout artwork.



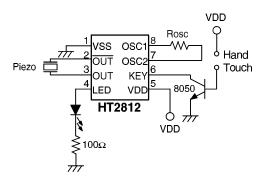
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Hand touch trigger



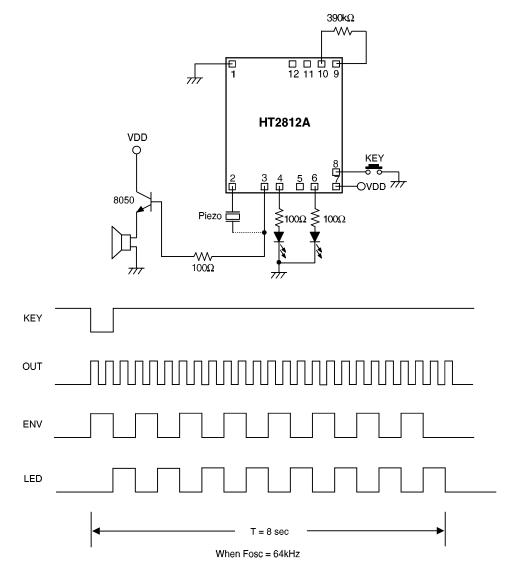
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### Application Circuit (HT2812A — Airplane)

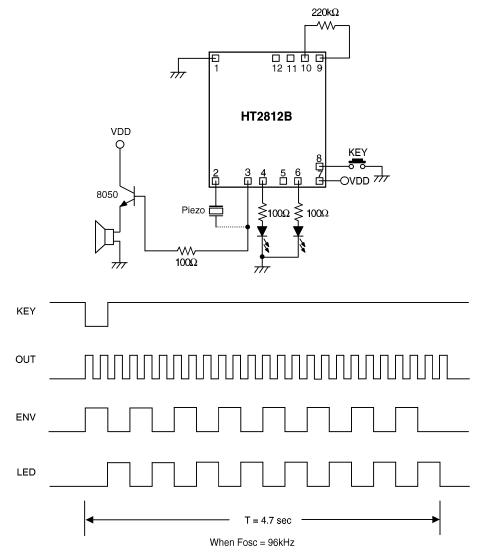


\* The IC substrate should be connected to VDD in the PCB layout artwork.

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### Application Circuit (HT2812B — Rocket)

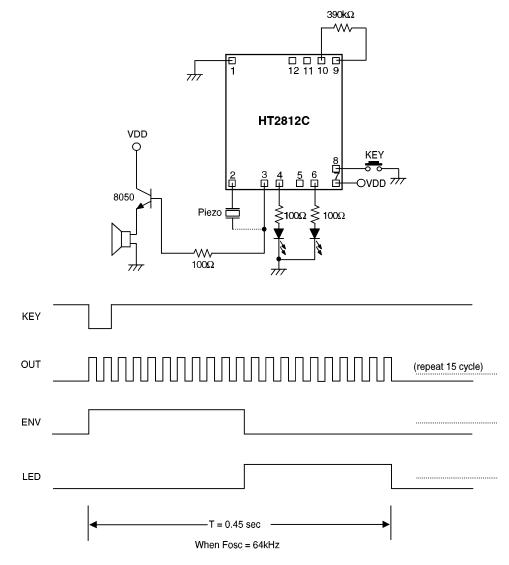


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### Application Circuit (HT2812C — Siren II)

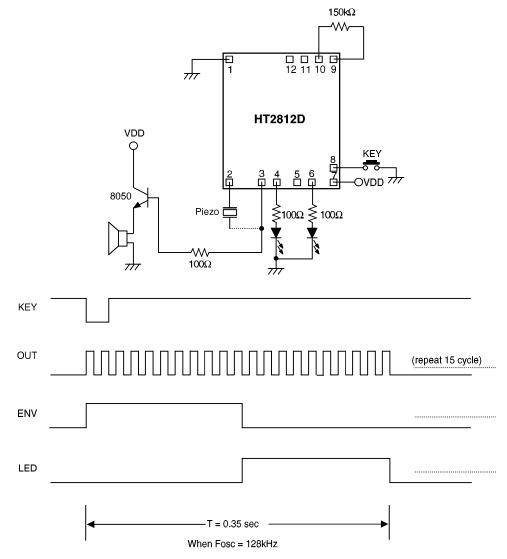


\* The IC substrate should be connected to VDD in the PCB layout artwork.

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### Application Circuit (HT2812D — Police Car)

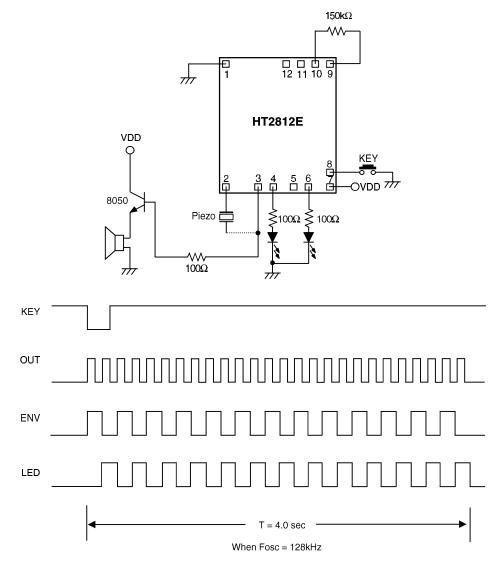


\* The IC substrate should be connected to VDD in the PCB layout artwork.

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### Application Circuit (HT2812E — Fire Brigade)

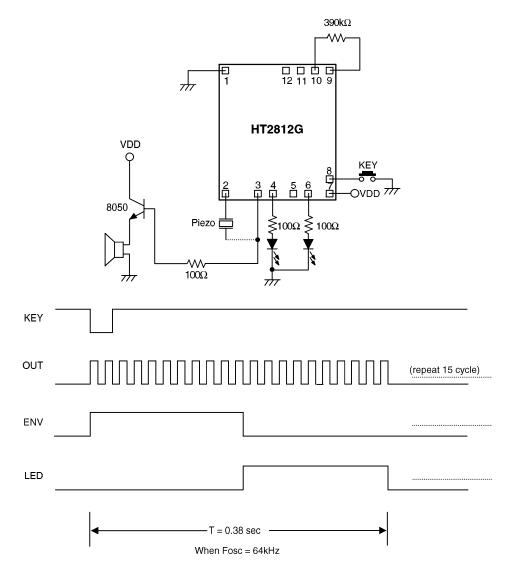


\* The IC substrate should be connected to VDD in the PCB layout artwork.

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### Application Circuit (HT2812F — Siren I)

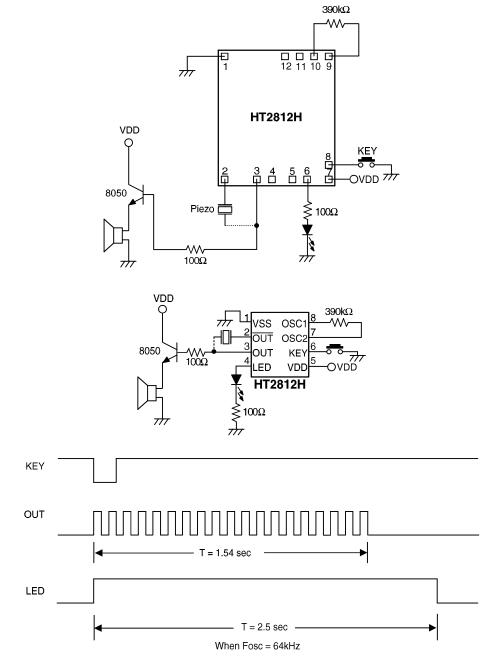


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### Application Circuit (HT2812H — Dialing Tone)

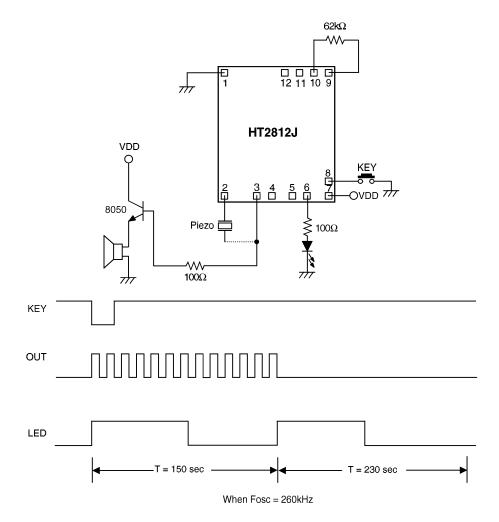


\* The IC substrate should be connected to VDD in the PCB layout artwork.

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### Application Circuit (HT2812J — Chicken Sound)

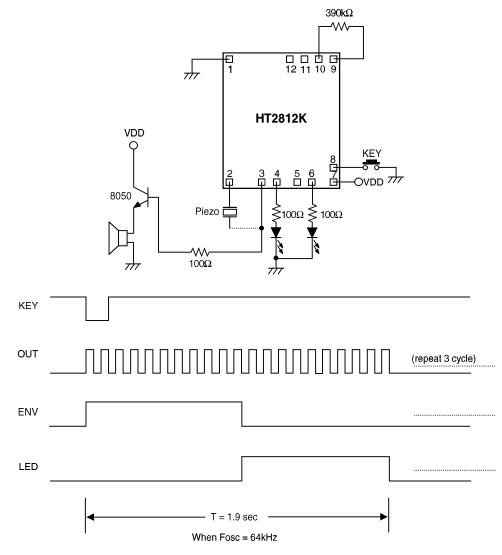


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### Application Circuit (HT2812K — Ambulance Sound)



\* The IC substrate should be connected to VDD in the PCB layout artwork.

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